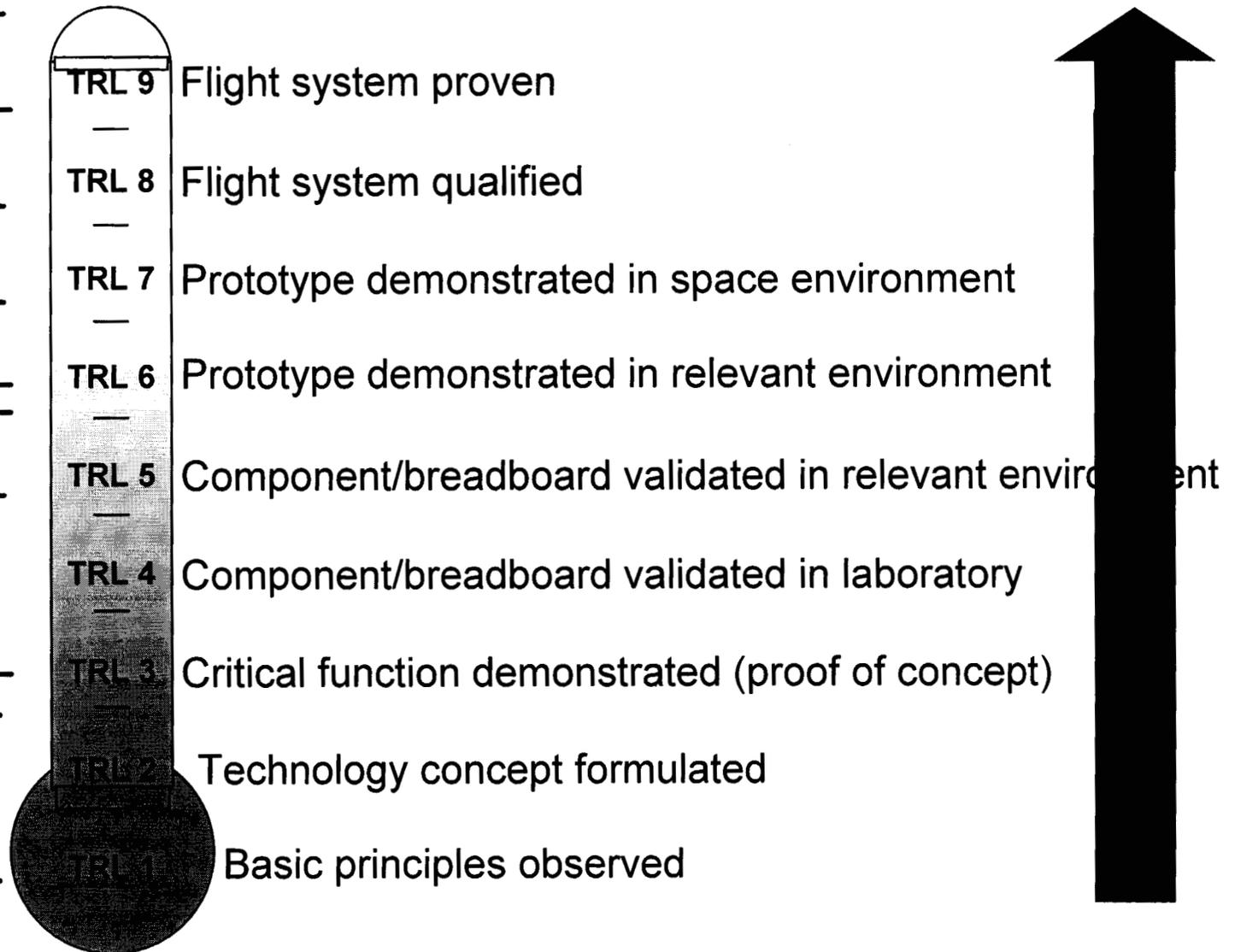


Paula.Grunthner@jpl.nasa.gov
In Situ Technology & Experiment Systems

Topics

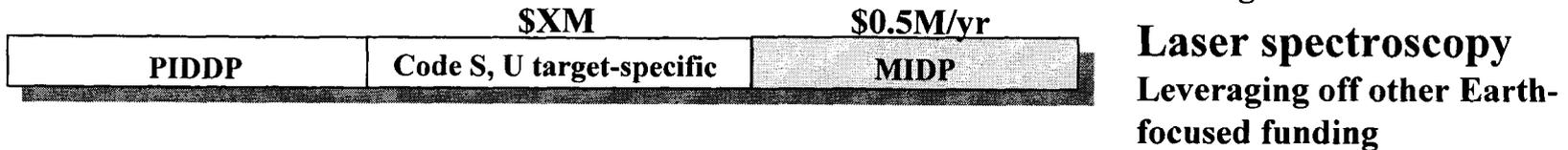
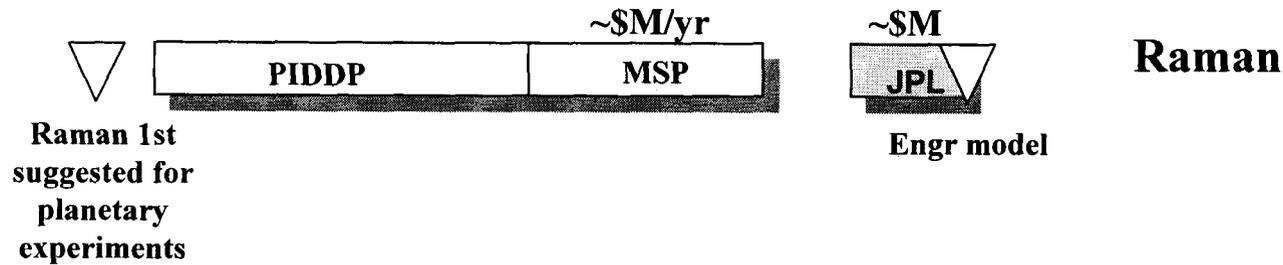
- **Example timelines for instrument development**
- **What you should do now rather than later**
 - ↗ Bounding the scope
 - Functionality
 - Accommodations
 - Environments
 - ↗ Architecture and design issues
- **Development roadmap for an instrument**

NASA's Technology Readiness Levels



Development Timeline Examples

95 | 96 98 99 00 | 01 02 03 04 05 | 06 07 08 09 10 |



Functionality

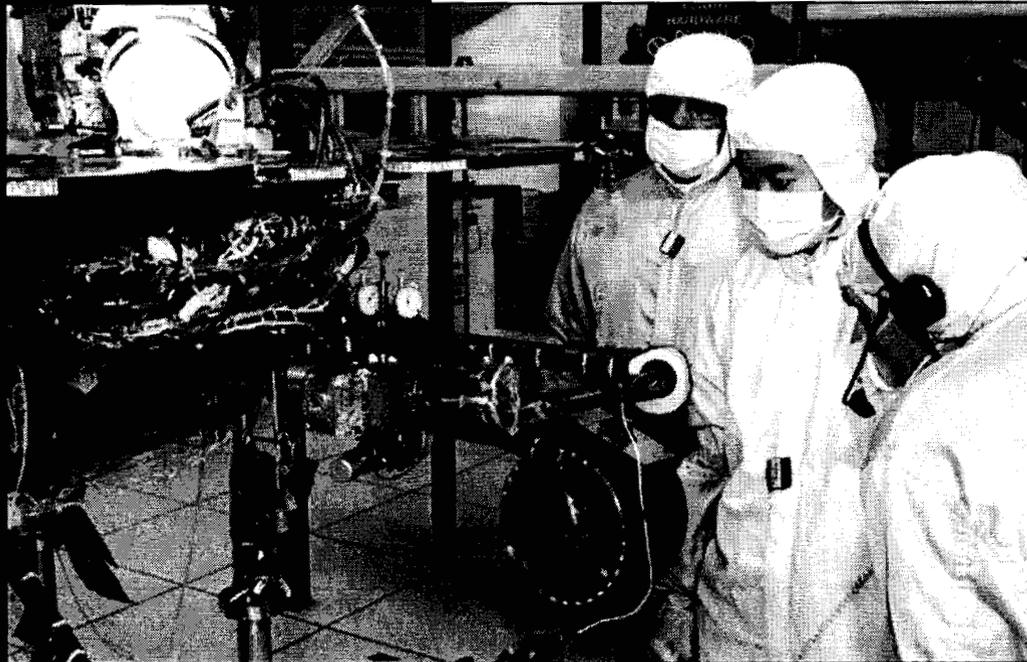
- **Map science objectives into system performance requirements**
 - ↗ Flush out issues related to meeting science needs
 - ↗ Solidify the goals of instrument performance
 - ↗ Will point to requirements on mission and host vehicle
- **Define expected science scenarios**
 - ↗ How will the instrument be used in meeting the science objectives
 - ↗ Look at the micro- and macro-scale operation from short-term sampling sequences through data acquisition strategies over the mission duration
 - ↗ Will further help define what the instrument and the host vehicle needs to do

Accommodations

- **The instrument draws on valuable host vehicle resources**
- **Practical considerations need to drive the instrument development for it to successfully compete for a ride**
 - ↗ 1.5–6 kg/instrument average on Mars Polar Lander
 - ↗ 5–28 ave Watts/instrument on Mars Polar Lander
 - ↗ Science payload on MSL ~35 kg, MER ~5 kg, MPF ~
- **You will need interfaces consistent with the host vehicle, especially if you expect to be able to demonstrate your instrument on prototype vehicles**
 - ↗ Look at past PIPs for examples
- **Many future missions have been scoped in terms of payload mass, volume, power. Research these to get a feel of severity of the constraint envelope**

Strive to be vehicle friendly...

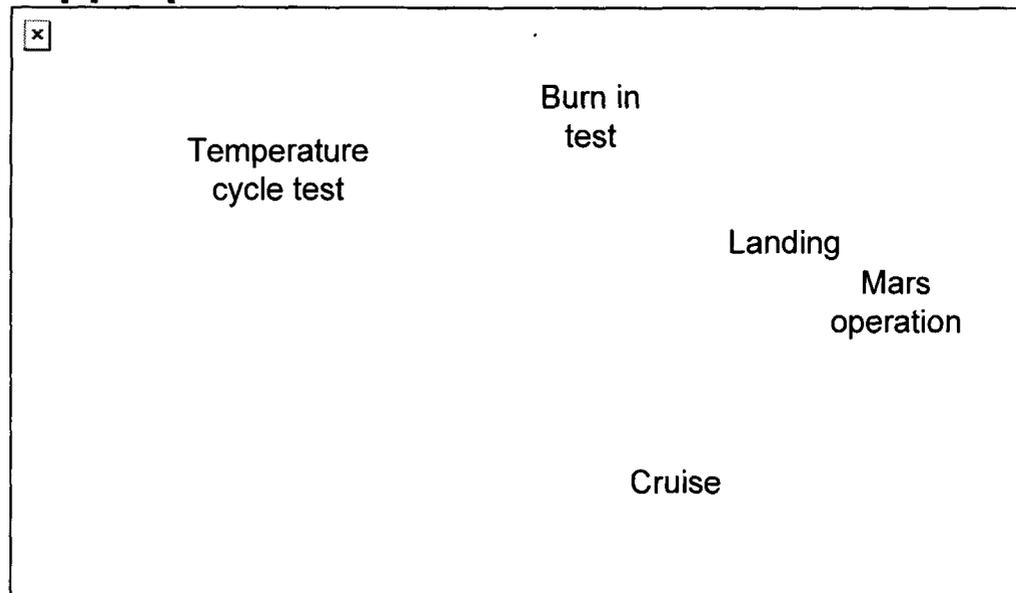
- **Wash U / JPL Raman missed its ride in part because it was not sufficiently rover friendly**
 - Required critical placement against rock
 - Delicate optical fibers connecting head and spectrometer
 - These interface issues placed unacceptable requirements on rover placement and the arm mechanism



- **Subsequently, the team has redesigned several components**
 - Effective depth of sampling now much greater, relieving placement constraints
 - Incorporated innovative jacketed fiber technology, providing needed robustness and tolerance for arm motion for storage and sampling

Environment

- **Consider all environments**
 - All phases of the mission
 - Ground-based demonstrations
 - Development testing
- **Temperature extremes—from transport to the launch vehicle to variations on the planet surface**
- **Radiation, pressure, humidity, wind, dust, UV, planetary protection**
- **Doing this now will help you end up with a risk-retired and appropriate instrument**



Things you should worry about sooner than later—

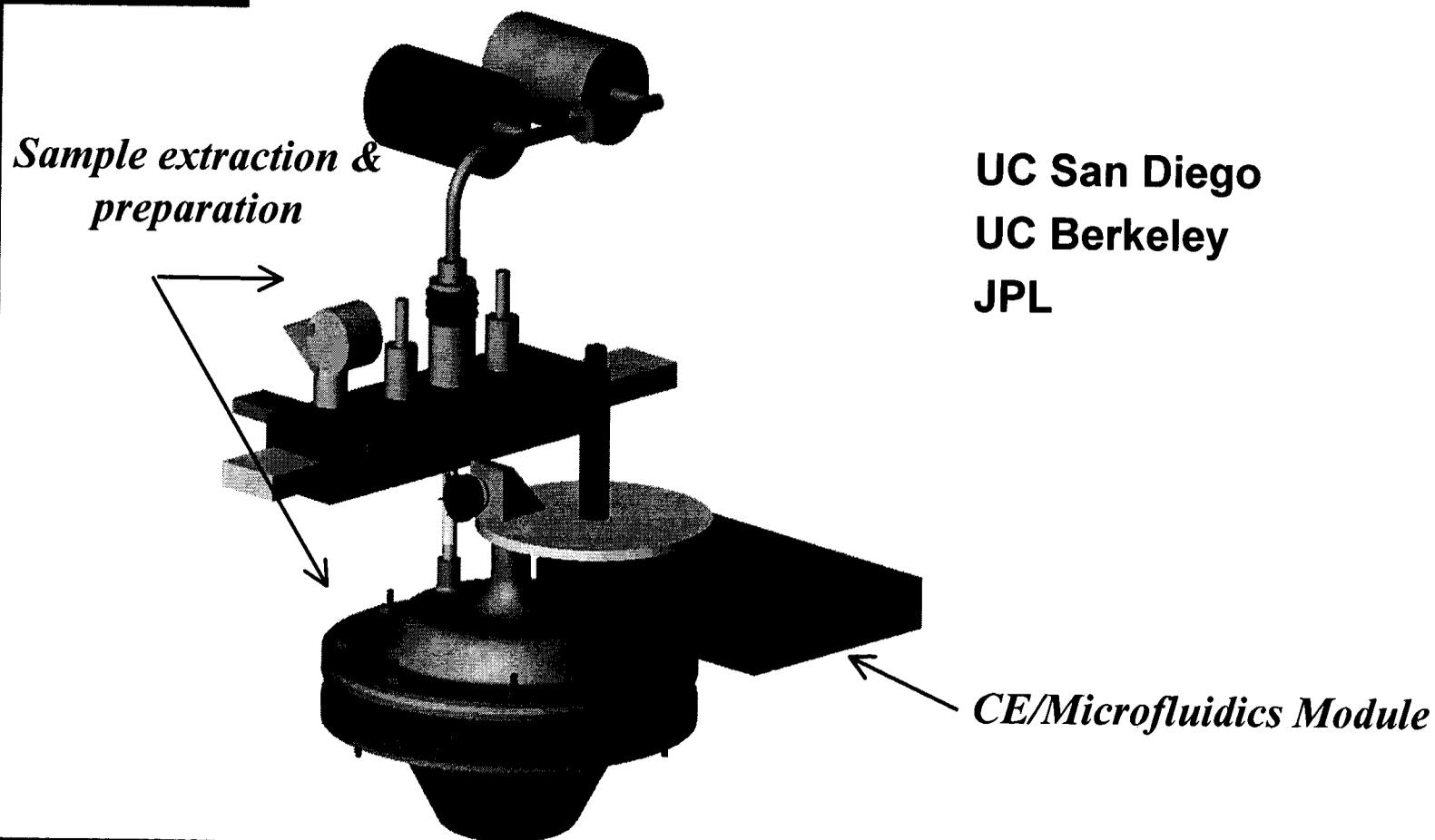
- **Relates mostly to a flight instrument, but early consideration can acceleration your development schedule considerably**
 - ↗ **Instrument architecture**
 - ↗ Margins
 - ↗ **Mechanical design**
 - ↗ **Thermal design**
 - ↗ **Electronics design, parts, and packaging**
 - ↗ Software
 - ↗ Optical design
 - ↗ **Reliability & Product assurance**
 - ↗ **Planetary protection & contamination control**
 - ↗ Ground support equipment
 - ↗ **Science calibration & performance validation**

Instrument Architecture

- **Produce a functional block diagram of the instrument**
 - ↗ Look at different ways to implement, considering the pros and cons of each
 - ↗ Develop a measure error budget caused by the design limitations and operational environment
 - ↗ Examine each possible implementation to see if it offers any advantages in terms of redundancy or partial success in the event of a failure
 - ↗ Compare mass, power, performance, reliability, and cost—then select the instrument architecture

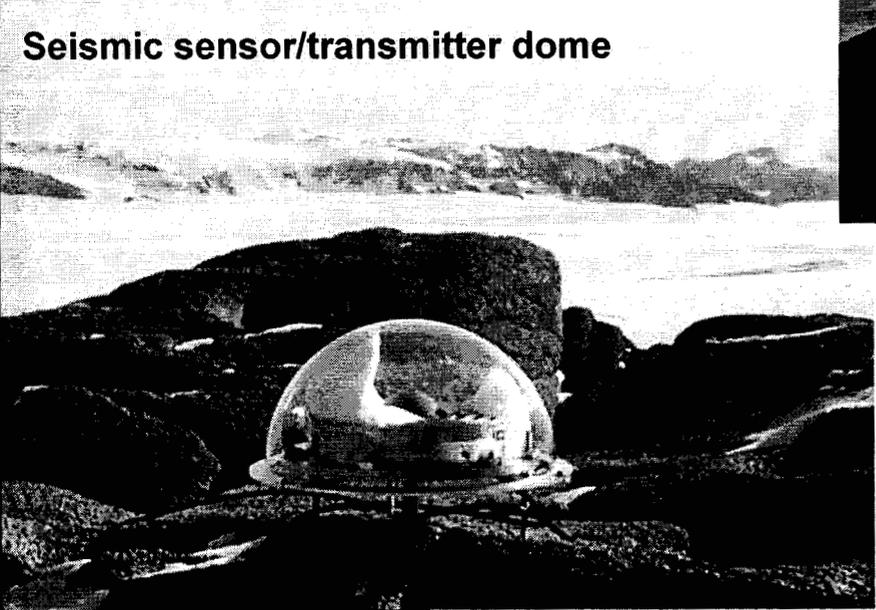
Instrument Architecture

- Don't leave sample handling and preparation for the end!

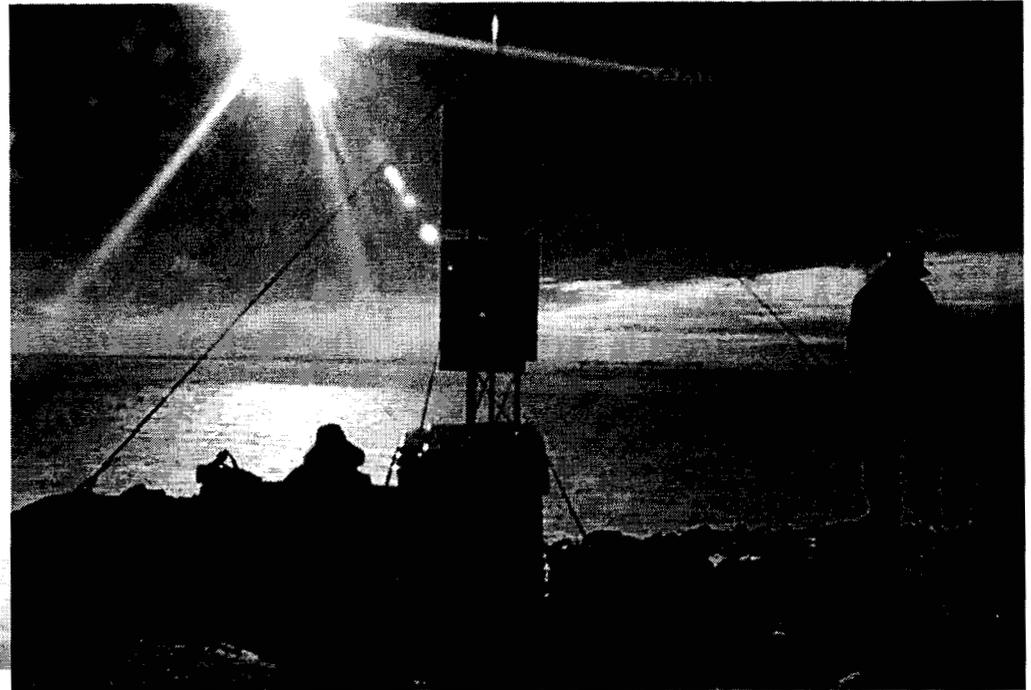


Thermal Design

- **Thermal control—scheme to manage the energy flow to achieve a desirable thermal state**
- **Determine all possible external & internal environments**
 - ↗ Temperature: extreme high/low, diurnal variations
 - ↗ Atmosphere: high/low pressures, vacuum, opacity
 - ↗ Solar flux intensity/variation, incident angle, duration
 - ↗ Wind speeds/direction, dust storms, humidity
 - ↗ Additional external s/c, orbiter, lander structures for thermal radiation interaction
 - ↗ Thermal dissipation of electronics & other devices as $f(t)$
 - ↗ Physical configuration of s/c and orientation
- **Can instrument be kept within allowable flight operating and non-operating temperatures?**
 - ↗ Passive control— isolation or enhancement of radiative & conductive/conventive surfaces (insulation, surfaces with special IR emissivity/solar absorptivity, standoffs, baffles)
 - ↗ Active control—the addition or removal of heat (heaters or pumped fluid system)



Seismic sensor/transmitter dome



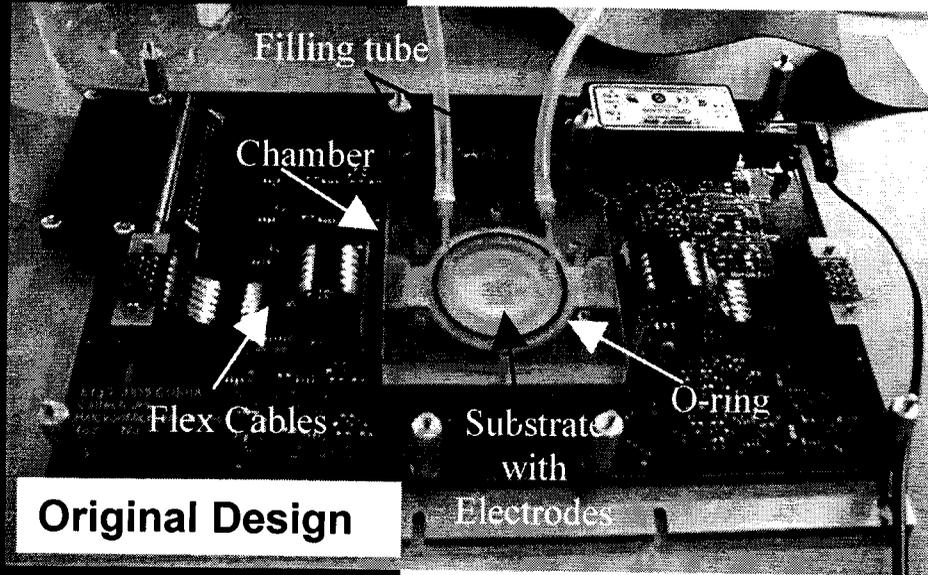
- **Ambient Temperatures Similar in Extremes and Diurnal Variation**
 - **Wind Conditions Similar in Unpredictable Wild Changes**
 - **Solar Conditions Could Be Low on the Horizon**
-
- **Similarities in thermal design for equipment assembly**
 - Insulation enclosure to minimize overall heat losses
 - Thermal coupling of equipment components to maximize thermal inertia

Electronics Design, Parts, Packaging

■ Part selection

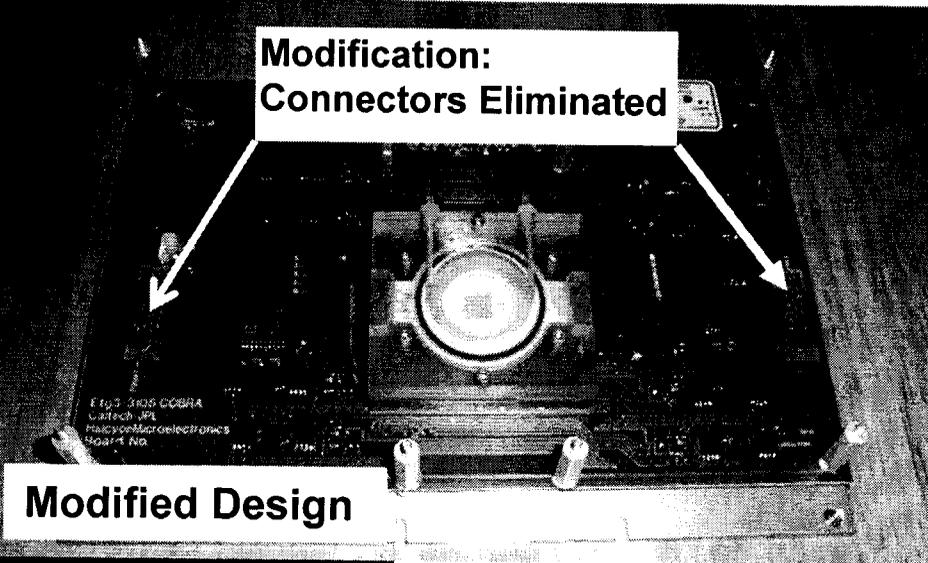
- Breadboard—demonstrate functionality of design; commercial parts OK
- Brassboard (engineering model for flight)—“form, fit and functionally equivalent”
 - All interfaces (mechanical, structural, thermal, electrical) flight-like and resource targets met
- Flight model—all parts must meet the environmental and reliability requirements (with margins) specified for the mission
 - Includes temperature, total dose ionizing radiation, single-event effects
 - Example: parts rated to 20 Krads must be used for a mission expecting 10 Krads exposure with a rad design margin of 2
- Most COTS devices have unknown reliability—screening & qualification evaluation will have to be done
- Do a part list review when you transition from bread to brassboard

Part Availability Issue



■ Design Principle:

- Designer must identify part availability issues
- Gather all parts before beginning design



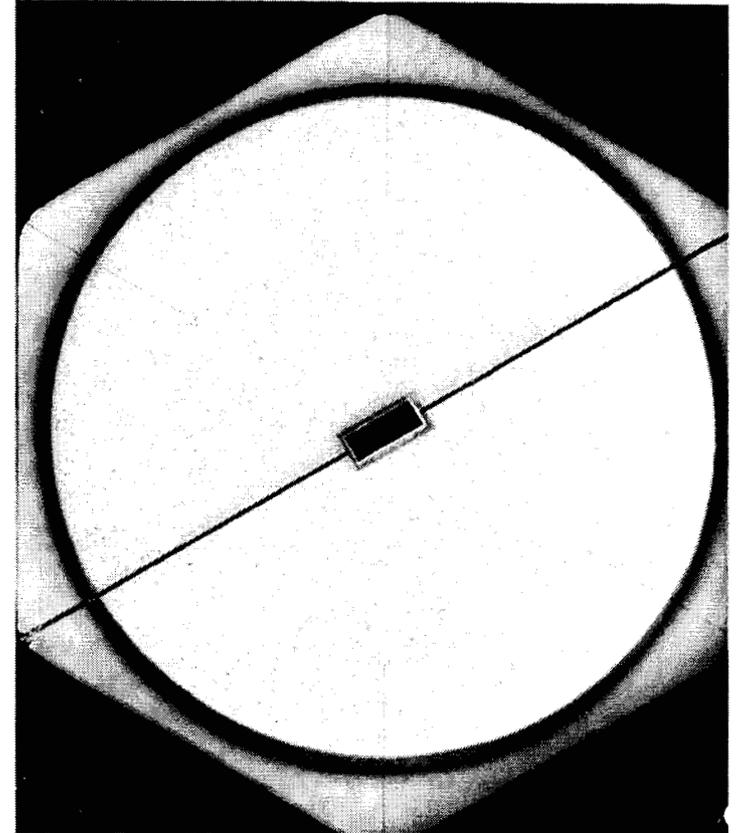
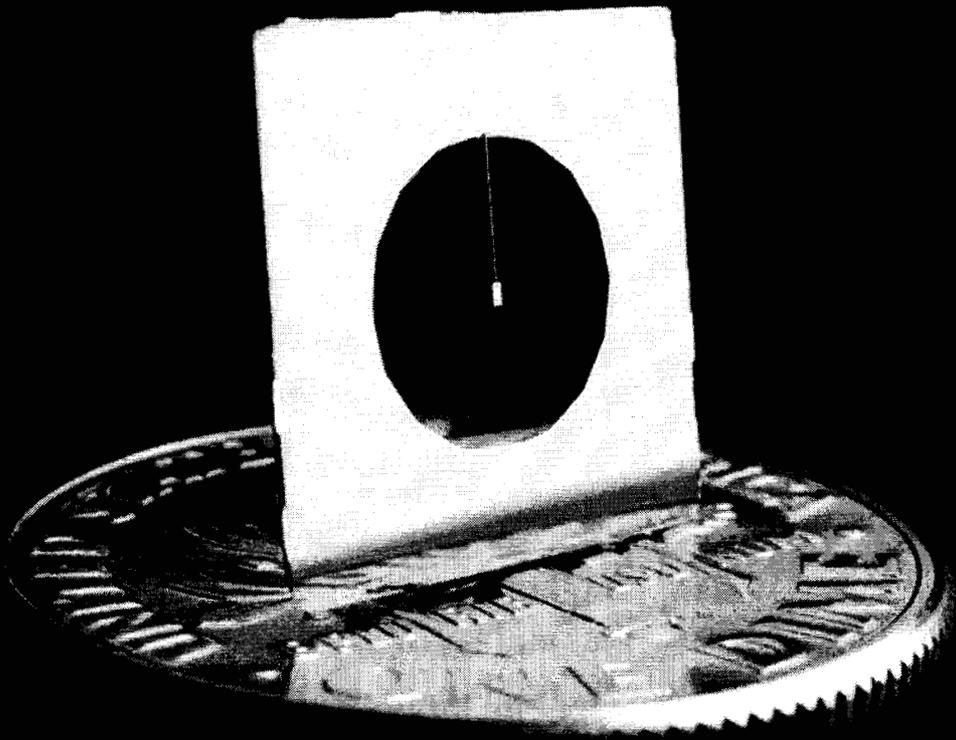
■ Example: Electronic tongue

- Connectors assumed available
- Part supplier wanted \$6,000 to manufacture 3000 parts with 12 month delivery
- Solution: Redesign to utilize available connectors

Electronic tongue

Advanced Electronic Packaging

- Advanced packaging can improve performance and save resources



- Lack of significant space track record means higher risk—money & time is needed

Mechanical Design

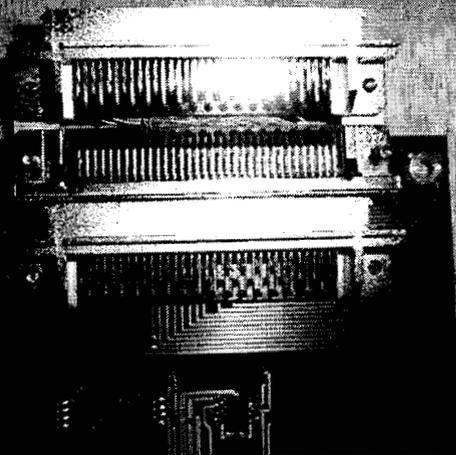
- **Reducing a workbench-sized breadboard to fit within the constraints of a flight instrument requires materials, packaging, and fabrication techniques to be traded off to optimize mass, volume, strength and cost**
 - Configuration is the key—establish the “big picture” layout with CAD before you dive into details (will change as the instrument matures or requirements change)
- **Think about the flight load—**
 - maximum structural loading your instrument may see during all expected conditions including launch, cruise, landing, ground handling, and thermal environment
- **Al alloys are common for brassboards**
 - As you approach flight-like, Al, various steels, Ti, and composite laminates (to mention only a few) will likely be needed for strength, weight, and functionality.
- **Outgassing, CTE mismatch, embrittlement at cold temperatures, galling... should have your attention**

Tips from the ME's

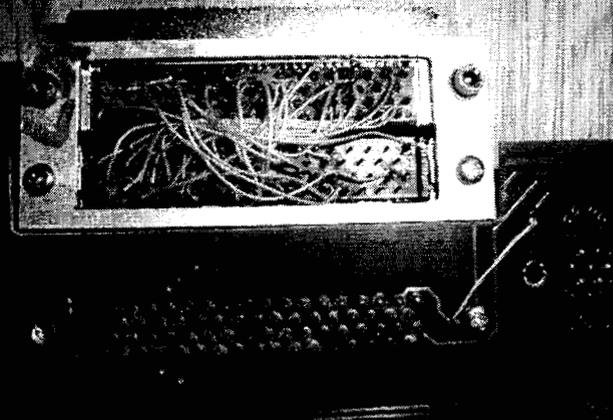
- **Mechanisms design (pointing systems, deployment systems, pyro devices, covers, latches, booms, etc.)—require a broad range of engineering disciplines and tools**
 - Use kinematic designs where ever possible
 - The vast number of mechanisms employed in flight systems have resulted in comprehensive references
- **Use a single fabrication shop—experience has shown that there is a consistent savings in cost of 25 to 100% when fabricating new mechanism systems**
- **Precision parts machined at one vendor at 25°C and another at 22°C can make a difference in tolerance stack-up**
- **Practices that ensure high reliability**
 - Simplicity of design
 - Avoid cost-saving measures that are likely to lower reliability
 - Use designs that compensate for potential human errors
 - Use parts & materials with proven heritage
 - Tight controls on the manufacturing process
 - Design to accommodate the effects of transportation, handling, & storage

Fit Check Issue

Connector adapter



Cross wired connector



■ Design Principle

- ↗ Designer must reduce “lack of fit” issues.
- ↗ Recommendation: Gather all parts and perform fit check using the CAD drawings.

■ Example

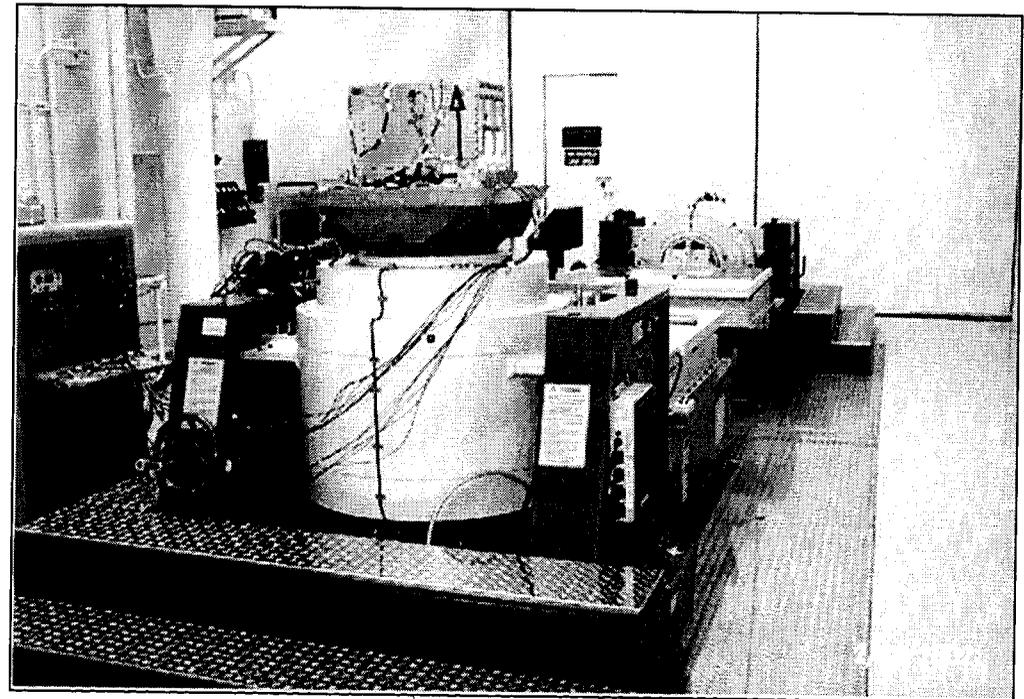
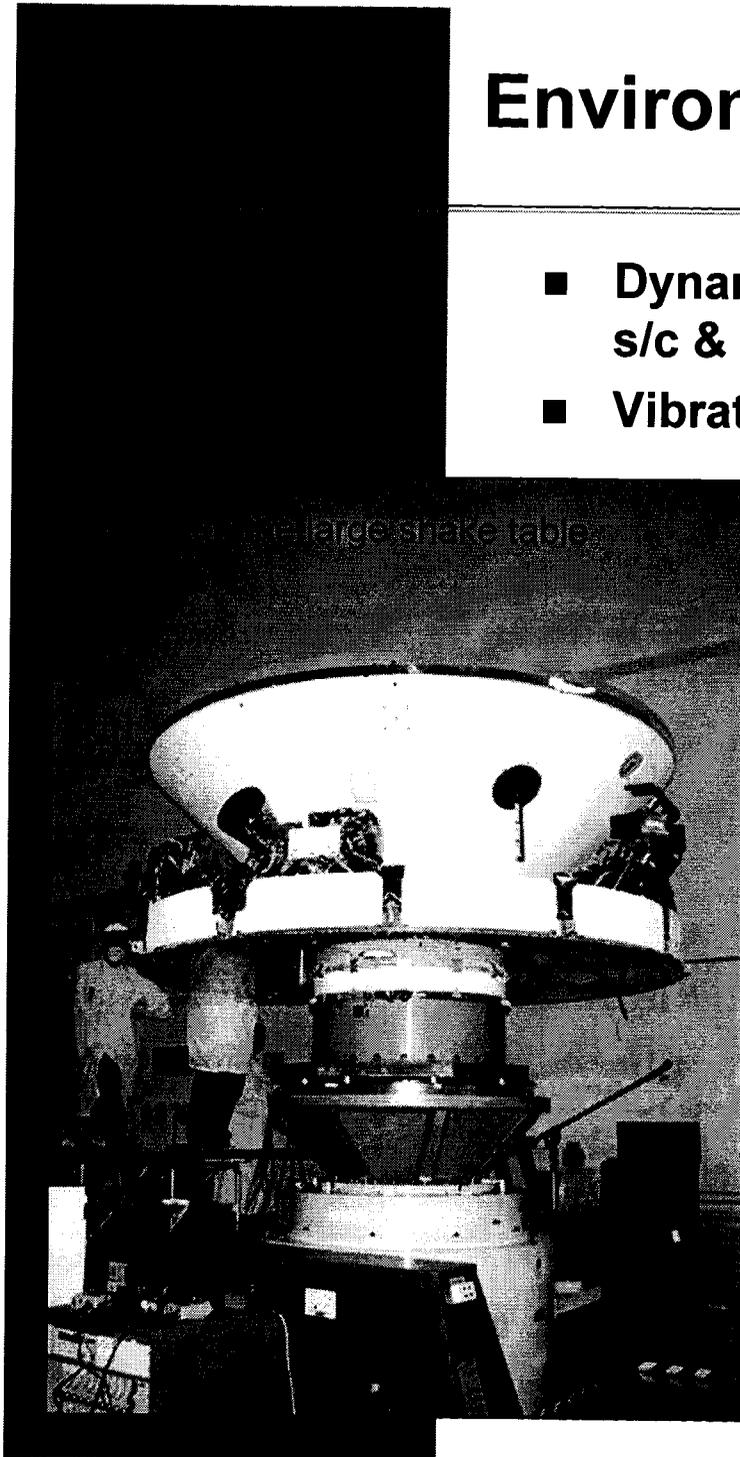
- ↗ Connector wired backward.
- ↗ Solution: Fabricate an connector adapter and cross wire.
- ↗ Redesign electronics board to correct the problem.

Reliability Assurance Engineering

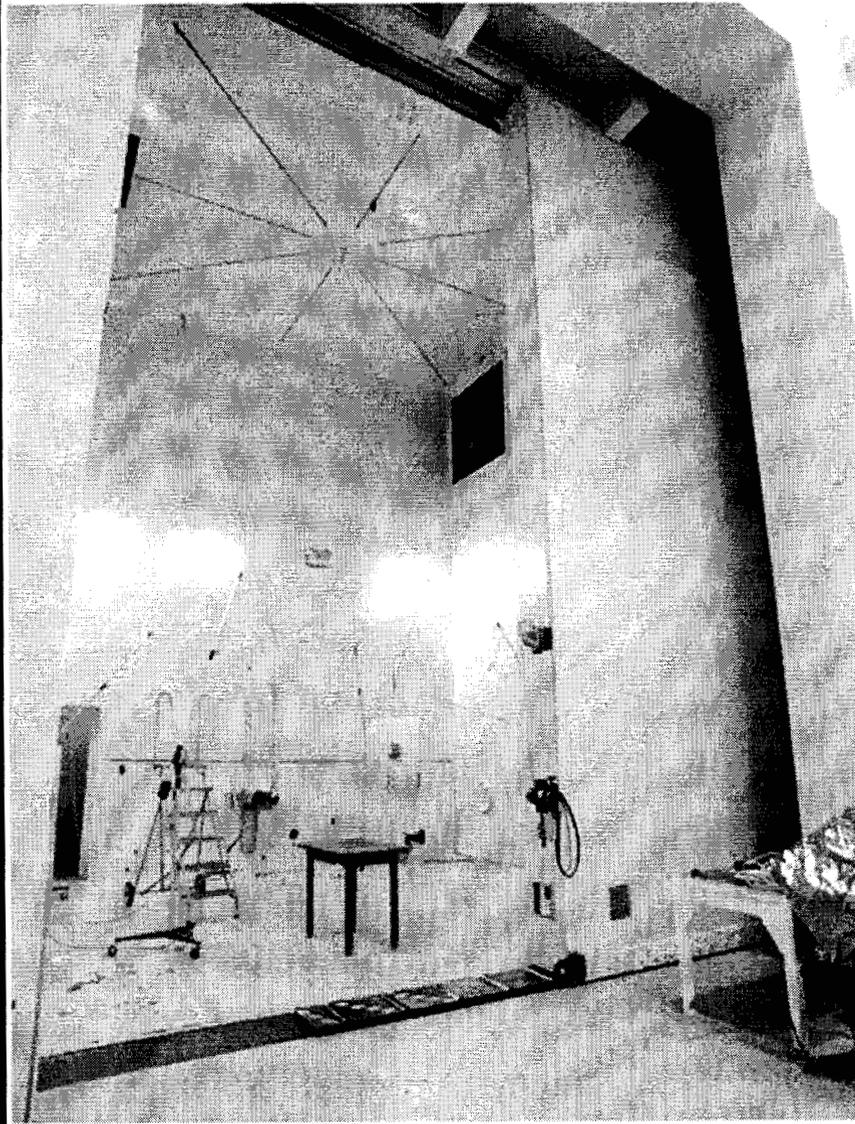
- **Environmental requirements and testing**
 - Ground, transportation, launch, cruise, orbit, entry, descent, and landing environments
- **Reliability analysis**
 - Various analysis techniques to validate functionality under flight conditions: failure scenarios, extreme operating conditions, etc.
- **Quality assurance**
 - Assure delivery of all project requirements
 - Ensure deliverables are developed according to a quality process
- **Problem/failure reporting**
 - Controlled, closed-loop system for identification, reporting, analysis, corrective action, and retest
- **Safety**
 - Personnel and equipment safety is as important as project achievement & risk tolerance

Environmental Test: Launch Vibration

- Dynamic environment driven by launch vehicle and s/c & instrument configuration
- Vibration, acoustics, and shock
 - JPL has 4 vibration exciters, 10,000 to 58,000 force pounds and displacement of 1.5-inch double amplitude
 - Pyroshock up to 2,000 gs



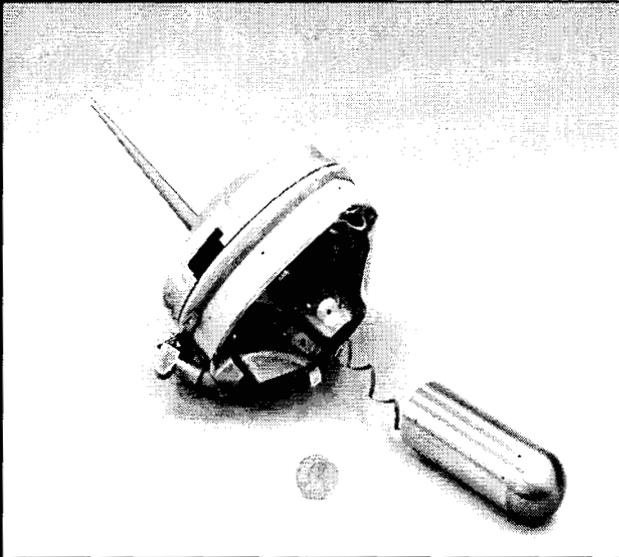
Environmental Test: Acoustic



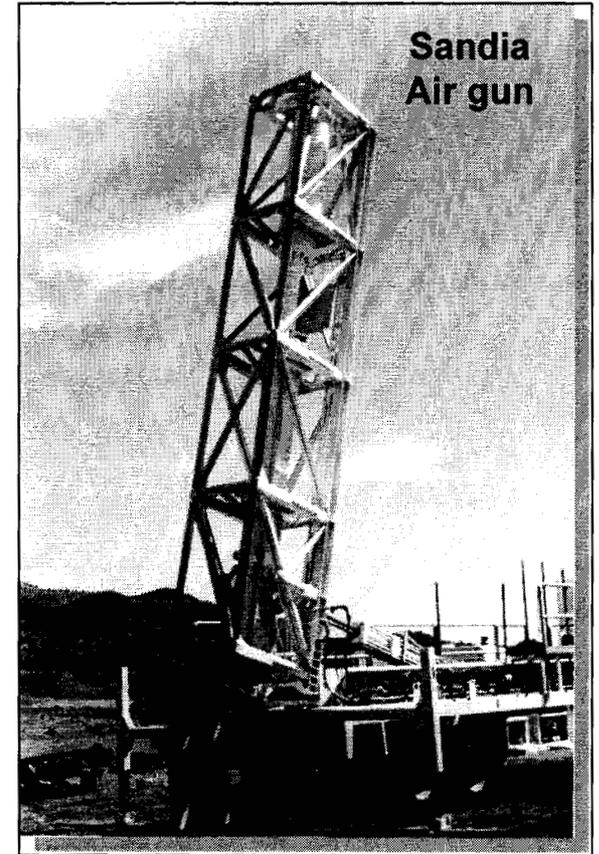
- **Simulates noise generated at liftoff**
- **Acoustic noise chamber**
 - 10,900-cubic-foot reverberation chamber capable of 155 dB
 - 22 feet wide, 18 feet deep, 26 feet high
- **Large, Class 10K clean room**

Acoustic Reverberation Chamber

Impact Extremes—DS2

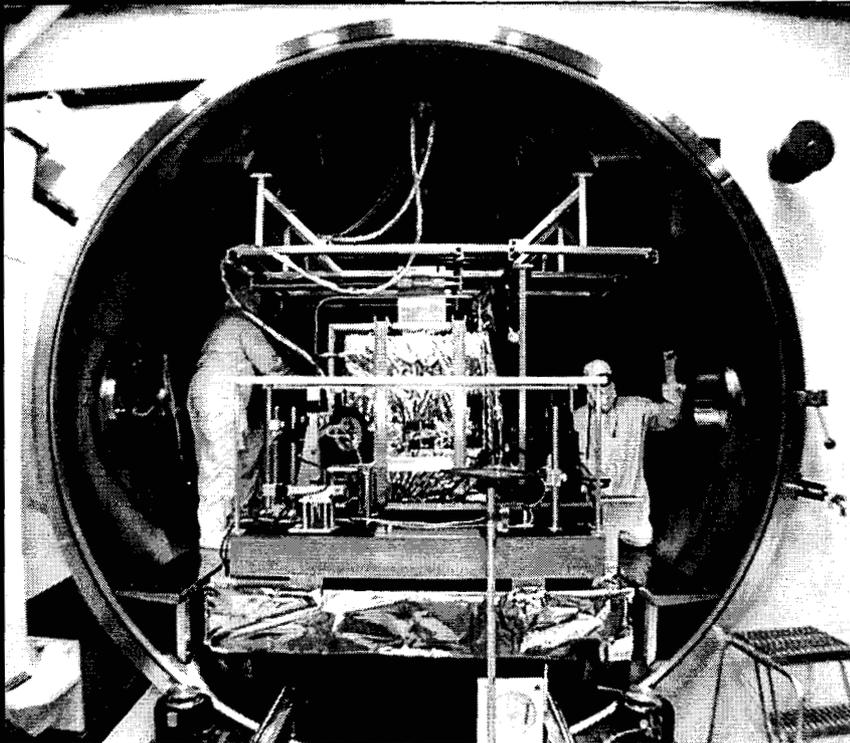


- SiC backbone, electronics with microcontroller, power electronics, instrument electronics, motor, drill
- Science TDL, temperature sensor, accelerometer



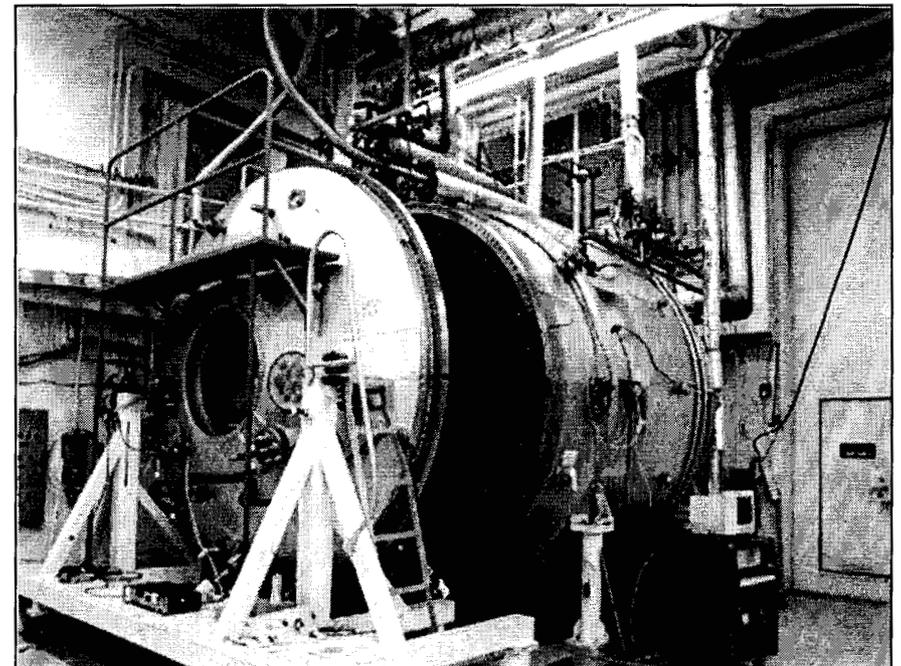
- 30,000 (fore) to 60,000 (aft) Gs deceleration at impact

Environmental Test: Thermal-Vacuum



11-ft thermal-vacuum chamber

- Important to include transient analysis from one extreme to another (cycle)
- DS2 forebody tested from +20°C to -120°C

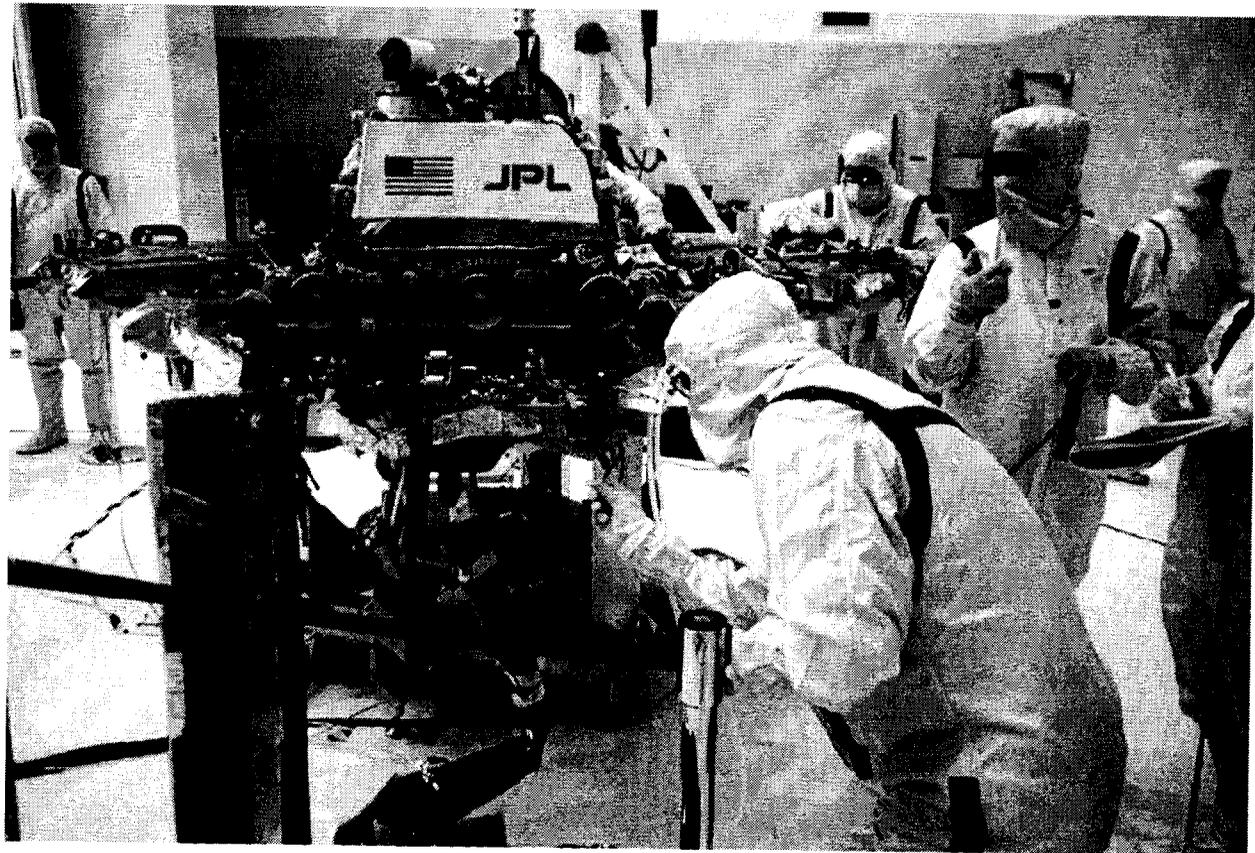


10 ft dia x 8 ft deep thermal-vacuum chamber

- ↗ 3 to 25-ft dia chambers
- ↗ Solar simulator up to 2.7 Suns
- ↗ $1E10^{-6}$ Torr and temperatures from -185 °C to +130 °C

Planetary Protection & Contamination

- Contamination control (particulates & molecular contamination) versus planetary protection (biological & organic contamination)



H/W Requirements for PP

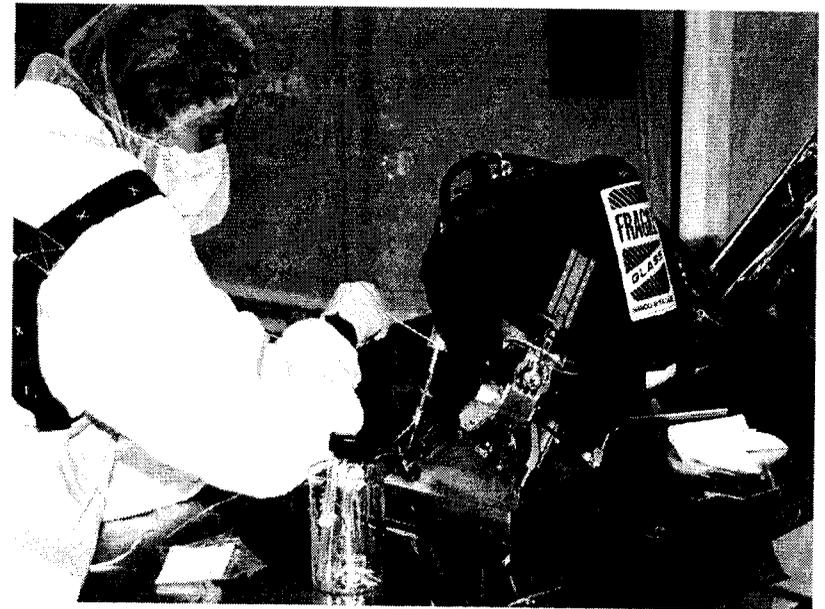
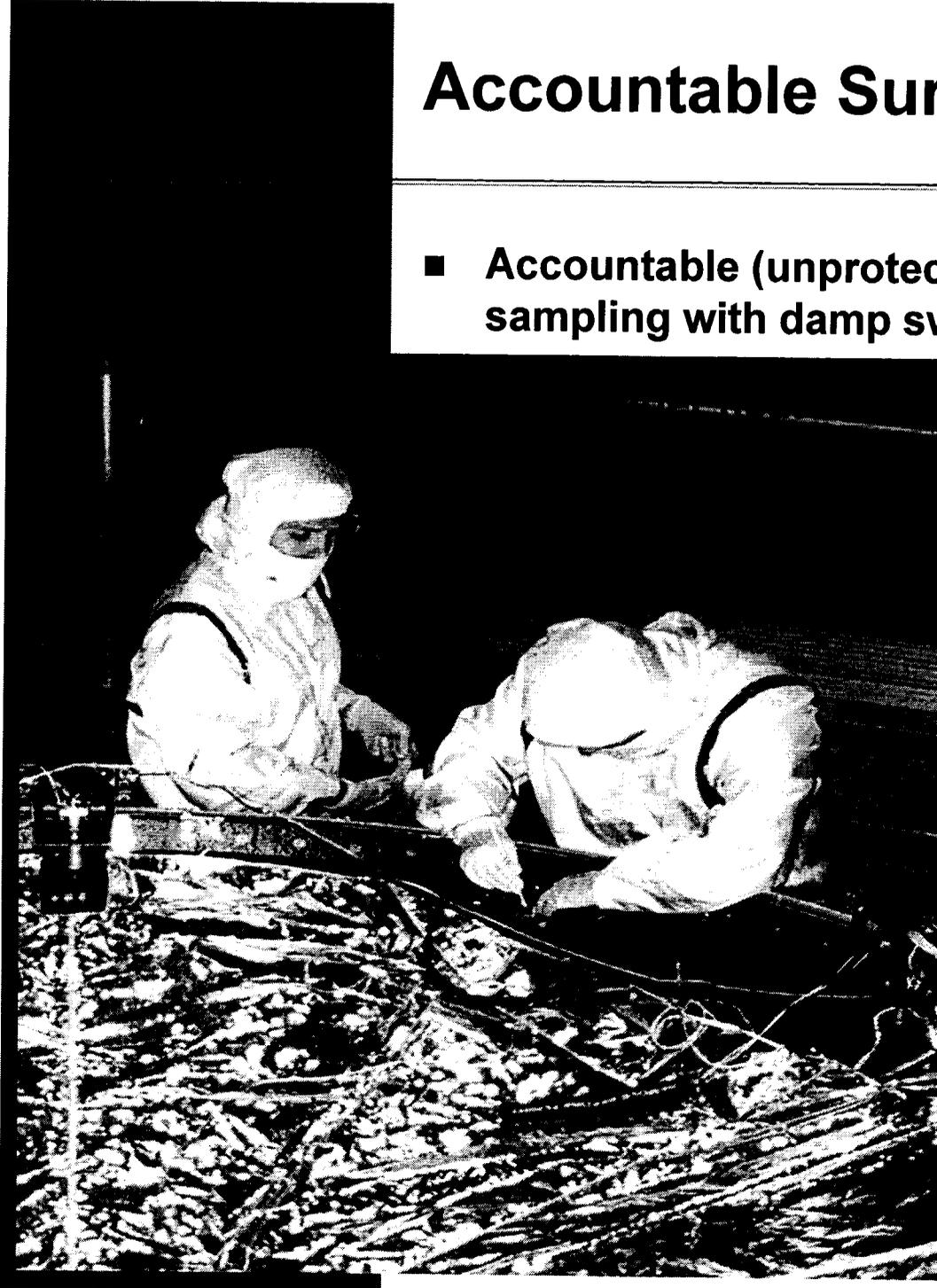
- **Category III: orbiters to Europa; Mars orbiters without adequate orbital lifetime**
 - ↗ Class 100K clean room assembly/maintenance
 - ↗ Stringent limit on spores (bacteria) on surfaces, in joints, and in the bulk of nonmetallic materials (total spores)
 - ↗ Organic material inventory (archival samples of materials present in large quantities)
- **Category IV: landers or probes to Mars and Europa**
 - ↗ Without life detection, Category IV-A: as above, except stringent limits on accountable (unprotected) surfaces only
 - ↗ With life detection, Category IV-B: as above, but with the strongest limit on total spores (baseline is sterility)
 - ↗ Category IV-C: special places
- **Category V: Earth return**

Approaches for H/W with Rigorous PP Requirements

- **Designing for cleanability**
 - ↗ Smooth surfaces
 - ↗ Accessibility before closeout
- **Minimizing accountable surfaces**
 - ↗ Isolation by high-efficiency particulate air (HEPA) filters or sealing
- **Designing for microbial reduction**
 - ↗ Tolerance for process (e.g., heat at 105°C or more)
 - ↗ Especially important for impacting hardware, with bulk spore burdens
- **Designing for recontamination prevention**
 - ↗ Closed at closeout (no gaps)

Accountable Surfaces

- Accountable (unprotected) surfaces must tolerate sampling with damp swabs or wipes



Swab sampling of surfaces on DS-2 microprobe assembly

Isolation by HEPA filter

- MPF on Mars by Sojourner camera, showing the integrated subsystem assembly (ISA) HEPA filter; interior of ISA exempt from burden account



Microbial Reduction Processes

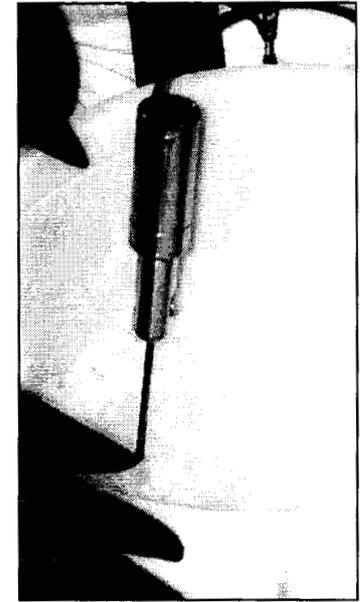
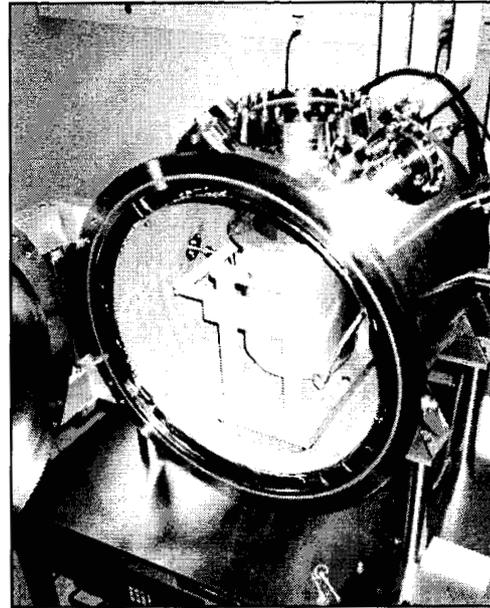
- **Dry heat microbial reduction**

- Process specifications exist
- Optimal in range of 110°C to 125°C (50 to 5 hours)



- **Hydrogen peroxide plasma**
 - Requires bioindicator or proxy
- **Other modalities (radiation, UV...) require validation**

R&D Instrument Performance Verification



- *In Situ* missions require realistic materials and environments in which to test and validate new technologies and systems to prove performance before flight and operation
- Conduct extensive testing and simulation in conditions as similar to actual flight conditions as possible
- Develop simulants according to ISO and ASTM standards with full documentation

Conclusion

■ **Develop a roadmap for your instrument**

- ↗ Consider both risk and practicality
- ↗ Concretely assess your design/technology issues & define how to reduce the risk in each (a brief risk management plan)
- ↗ For each risk, identify potential consequences and what mitigation strategies can be taken (and by when).
Focus on—
 - Where you might have trouble meeting functional requirements
 - Where the technology is not ready
 - Where you might not have enough schedule to develop/procure
- ↗ You don't have the funds to develop a flight-worthy instrument, but you can demonstrate that there is a pathway should you be selected for flight

Acknowledgements

- **Contributors to Mars Miniature Instruments Resource Book**
- **Jack Barengoltz, Planetary Protection**
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